



## Material Content Data Sheet



Sales Product Name	SAK-XC2387A-56F80L AA			Issued		29. August 2013		
MA#	MA001034348							
Package	PG-LQFP-144-13			Weight*		1459.18 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	38.601	2.65	2.65	26454	26454
leadframe	inorganic material	phosphorus	7723-14-0	0.122	0.01		84	
	non noble metal	zinc	7440-66-6	0.489	0.03		335	
	non noble metal	iron	7439-89-6	9.785	0.67		6706	
	non noble metal	copper	7440-50-8	397.309	27.23	27.94	272282	279407
wire	noble metal	gold	7440-57-5	3.925	0.27	0.27	2690	2690
encapsulation	organic material	carbon black	1333-86-4	4.933	0.34		3381	
	plastics	epoxy resin	-	133.186	9.13		91274	
	inorganic material	silicondioxide	60676-86-0	848.443	58.15	67.62	581453	676108
leadfinish	non noble metal	tin	7440-31-5	9.120	0.62	0.62	6250	6250
plating	noble metal	silver	7440-22-4	3.110	0.21	0.21	2132	2132
glue	plastics	epoxy resin	-	2.539	0.17		1740	
	noble metal	silver	7440-22-4	7.616	0.52	0.69	5219	6959
*deviation	< 10%	Sum in total:			100,00			1000000

### Important Remarks:

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